

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
Chung-Kun Cho	12/23/2009
Myung-sup Jung	12/23/2009
Kwang-Hee Kim	12/23/2009
Jae-Jun Lee	12/23/2009
Kalinina Fedosya	12/23/2009
Mahn Jong Kim	12/23/2009
Chung Won Park	12/23/2009

**RECEIVING PARTY DATA**

Name:	Samsung Electronics Co., Ltd.
Street Address:	416, Maetan-dong, Yeongtong-gu
City:	Suwon-si, Gyeonggi-do
State/Country:	REPUBLIC OF KOREA

Name:	Samsung Electro-Mechanics Co., Ltd
Street Address:	314, Maetan 3-dong, Yeongtong-gu
City:	Suwon-si, Gyeonggi-do
State/Country:	REPUBLIC OF KOREA
Postal Code:	443-803

Name:	Samsung Fine Chemicals Co., Ltd
Street Address:	190, Yeochon-dong, Nam-gu
City:	Ulsan
State/Country:	REPUBLIC OF KOREA
Postal Code:	680-090

PROPERTY NUMBERS Total: 1

Property Type	Number

**501049773**

**PATENT  
 REEL: 023694 FRAME: 0873**

OP \$40.00 12645967

Application Number:

12645967

**CORRESPONDENCE DATA**

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PNK-0696

NAME OF SUBMITTER:

Ian J.S. Lodovice

Total Attachments: 3

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## ASSIGNMENT

WHEREAS WE, **Chung-Kun CHO** of LD Koron Apt. 101-1003, 890, Guwoon-dong, Gwonsun-gu, Suwon-si, Gyeonggi-do, Republic of Korea; **Myung-Sup JUNG** of Pureun-maeul Ssangyong Apt. 610-1501, Sunae-dong, Bundang-gu, Seongnam-si, Gyeonggi-do, Republic of Korea; **Kwang-Hee KIM** of 101, 1630-16, Bongcheon 11-dong, Gwanak-gu, Seoul, Republic of Korea; **Jae-Jun LEE** of Hwanggol-maeul Punglim Apt. 235-1101, Yeongtong 1-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea; **Kalinina FEDOSYA** of 19-61 Ivanova Str., Ulan-Ude, Russia; **Mahn Jong KIM** of Expo Apt. 306-402, Jeonmin-dong, Yuseong-gu, Daejeon, Republic of Korea; and **Chung Won PARK** of Sejong Apt. 105-1102, Jeonmin-dong, Yuseong-gu, Daejeon, Republic of Korea (hereinafter collectively referred to as the "ASSIGNORS"), have invented certain new and useful improvements in:

### **THERMOSETTING RESIN COMPOSITION AND BOARD USING THE SAME**

(hereinafter referred to as the "INVENTION") which claims priority to Korean Application Nos. 10-2008-0133800, filed on 24 December 2008, and 10-2009-0121466, filed on 8 December 2009; and for which we, said ASSIGNORS, have filed an application for a United States Patent (hereinafter collectively referred to as the "APPLICATIONS");

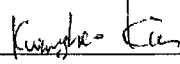
AND WHEREAS, **SAMSUNG ELECTRONICS CO., LTD.**, a corporation organized and existing under the laws of the Country of KOREA, having a place of business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea; and **SAMSUNG ELECTRO-MECHANICS CO., LTD.**, a corporation organized and existing under the laws of the Country of KOREA, having a place of business at 314, Maetan 3-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, 443-803 Republic of Korea; and **SAMSUNG FINE CHEMICALS CO., LTD.**, a corporation organized and existing under the laws of the Country of KOREA, having a place of business at 190, Yeochon-dong, Nam-gu, Ulsan, 680-090 Republic of Korea (collectively hereinafter referred to as the "ASSIGNEES"), are desirous of acquiring an interest in any and all countries, in and to the INVENTION, the APPLICATIONS, and any and all Patents to be obtained therefore;


NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for good and valuable consideration, the receipt of which is hereby acknowledged, we, the ASSIGNORS, have assigned and transferred, and hereby assign and transfer unto ASSIGNEES, the entire right, title and interest in and to the INVENTION, the APPLICATIONS, and any and all Patents that may be issued therefrom, in any and all countries, including any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to ASSIGNEES; and we do hereby agree that we will execute all papers necessary in connection with any and all patent applications when called upon to do so by ASSIGNEES, their successors or assigns, and that we will, at the cost and expense of ASSIGNEES, fully assist and cooperate in all matters in connection with any and all patent applications and Patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the APPLICATIONS or any Patents issuing thereon.

Date: 12/23/2009  \_\_\_\_\_ L.S.  
**Chung-Kun CHO**

Date: 12/23/2009  \_\_\_\_\_ L.S.  
**Myung-Sup JUNG**

Date: 12/23/2009  \_\_\_\_\_ L.S.  
**Kwang-Hee KIM**

Date: 12/23/2009  \_\_\_\_\_ L.S.  
**Jae-Jun LEE**

Date: 12/23/2009  \_\_\_\_\_ L.S.  
**Kalinina FEDOSYA**

Date: 12/23/2009

Mahn Jong Kim L.S.  
**Mahn Jong KIM**

Date: 12/23/2009

Park Chung Won L.S.  
**Chung Won PARK**